

Abstract

Method for transporting, chemical-mechanical polishing and drying of workpieces, in particular silicon wafers in a sealed clean room with the following steps:

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the workpieces are removed by at least one transfer device from a loading and unloading station and transferred onto an intermediate station

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the workpieces are received by at least one polishing head of a polishing device of the intermediate station, transported to a polishing plate of the polishing device and held under rotation of the polishing head against the rotating polishing plate

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after polishing, the workpieces are transported back by the polishing head to the intermediate station, released from the polishing head and cleaned and/or chemically treated in the intermediate station

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the cleaned and/or chemically treated workpieces are transported from the intermediate station optionally to a second polishing device or to a washing or drying device and washed and dried therein

the polishing head is cleaned before each workpiece is received.